

Grease

GREASE PRODUCT FAMILY

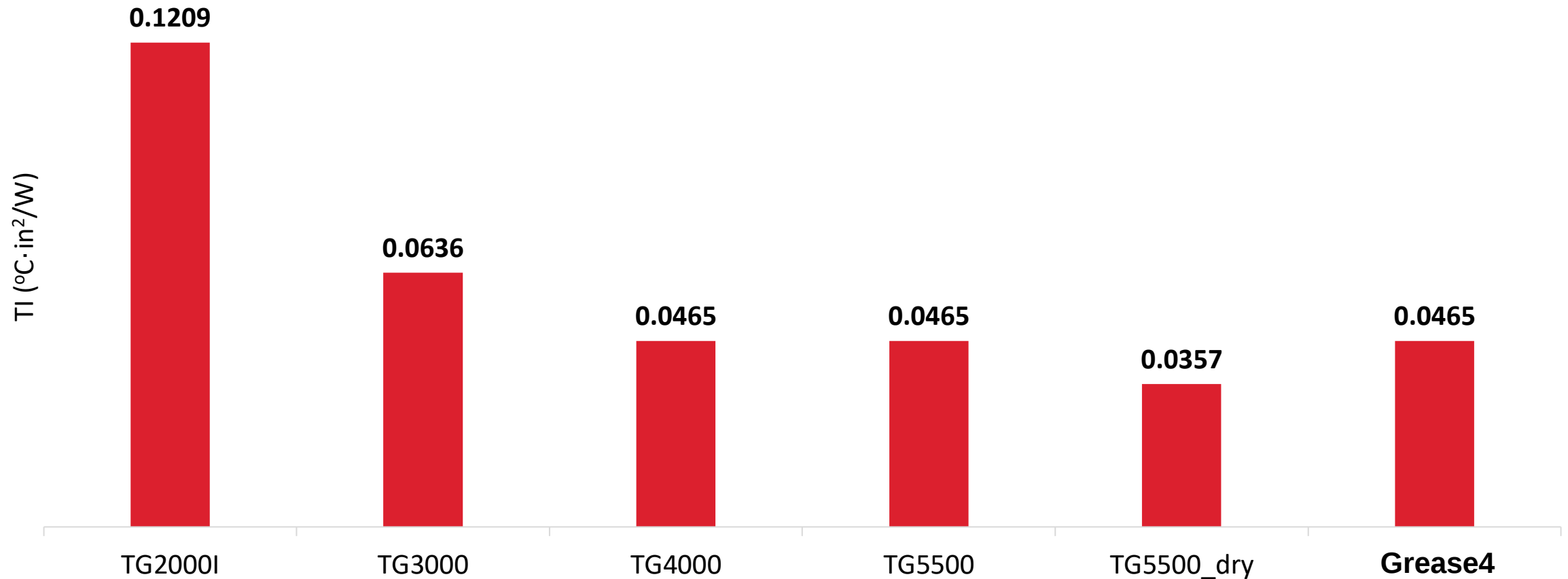
Property	TG2000I	TG2800I	TG3000I	TG3000	TG4000	TG5500
Min Bond line Thickness (micron)	50	25	7	25	23	40
Thermal Conductivity (W/m·K)	2.0	2.8	3.0	3.0	4.0	5.5
Thermal Impedance (°C·in²/W) (Thin BLT@50psi)	0.020	0.009	0.002	0.009	0.005	0.010
Solvent	W/O	W/O	W/O	W/O	W/O	W/ Solvent

* All value shown in table is typical measurement data

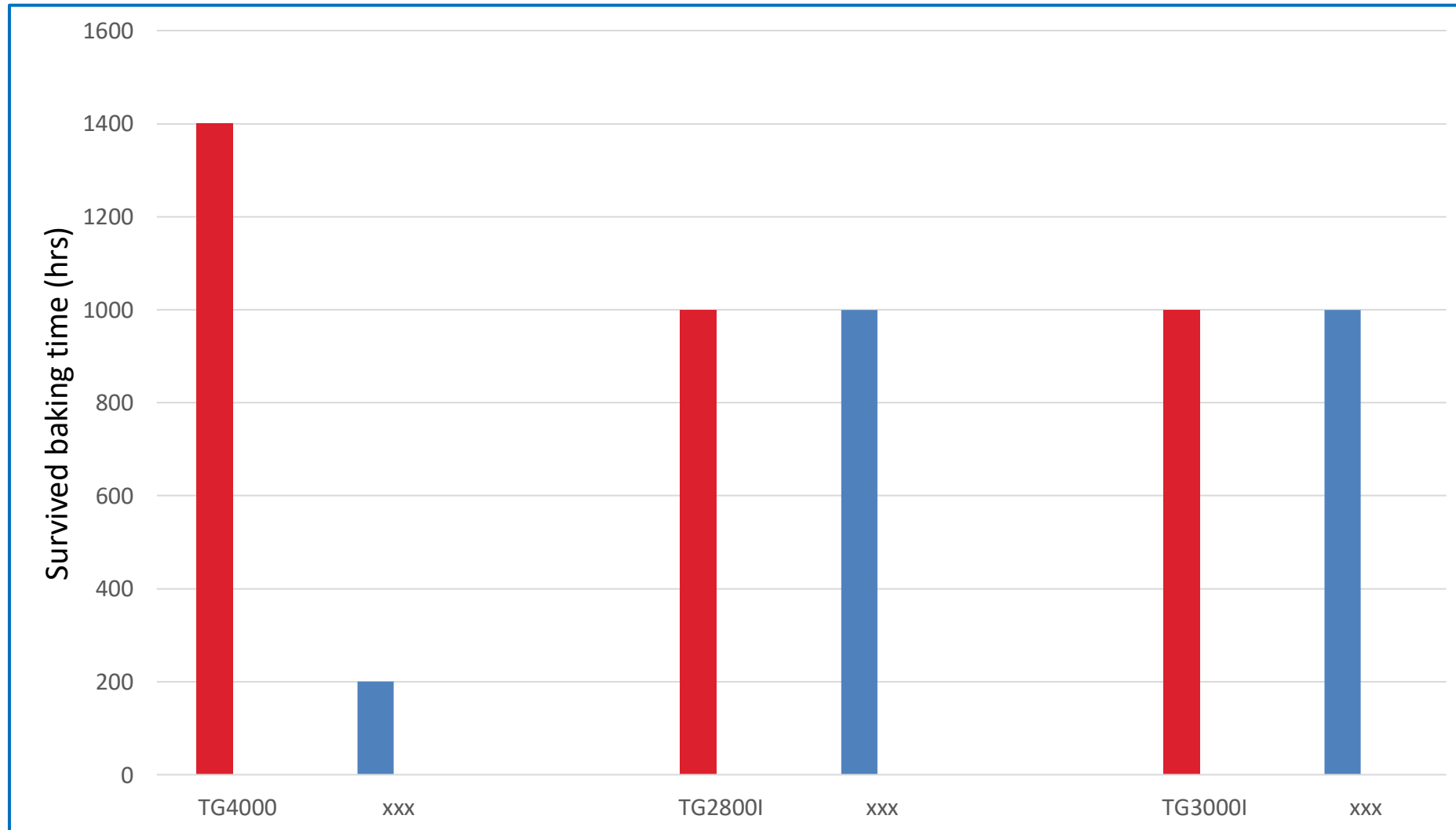
Different Formulation for Different Needs

THERMAL IMPEDANCE UNDER 5MIL

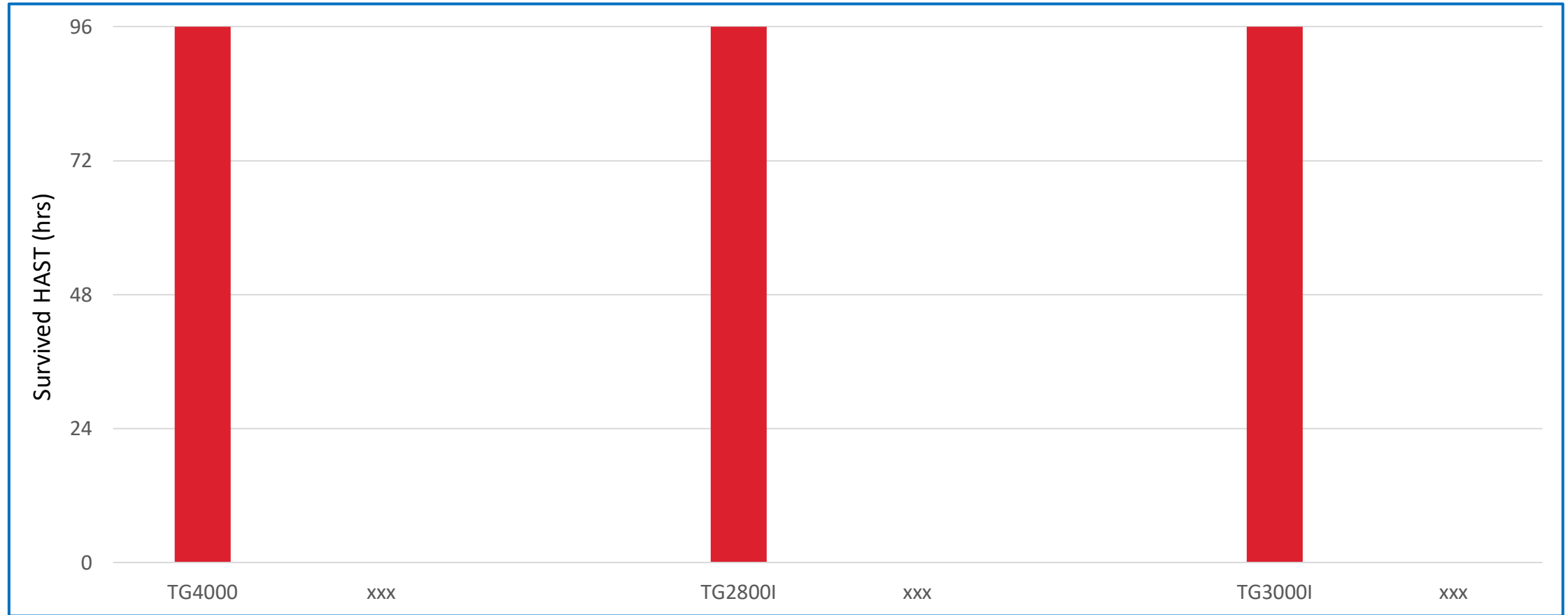
Thermal Impedance under 5 mil



THERMAL RELIABILITY – 150C BAKING



THERMAL RELIABILITY – HAST



THERMAL RELIABILITY – TCB

